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Rasmus Ischebeck

Imaging with Synchrotron Radiation: Tomography and Ptychography

Joint Universities Accelerator School



Micro-Tomography



ETH zürich

Microtomography principle







State-of-the-art SRXTM (1-50 um)









State-of-the-art SRXTM (1-50 um)



1 micron resolution routinely achieved at 10% MTF

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Propagation-based image formation



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The effect of propagation distance D = 5.000 mm

- Continuous data acquisition during camera motion
- Flat field corrected, shaking reduced



150 um

(c)2018, C.M. Schlepuetz, Swiss Light Source

Sample courtesy of E. Cörek, J. Huwyler, University of Basel

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In-situ 20 Hz tomographic imaging







- Crack propagation dynamics under tensile load
- 20 (!) 3D volumes per second

Movie playing in real time (9 seconds, 180 frames)

Maire et. al., Int J Fract (2016)



Imperial College London





How does a fly really fly?



Wings beat at 150 Hz !!

2500 X-ray images per second...



Imperial College London





Muscles and tracheal network during flight



Walker et al., PloS Biology (2014); Mokso et al., Sci Rep (2015)

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3 28 March 2014 Science & Environment

Complex image analysis and data interpretation



Donoghue et al (2006) Nature 442:680-3

Markuelia, the first "predator" on earth



Donoghue et al (2006) Nature 442:680-3



Access 3D information via computed tomography dotain many projections of the sample at different angle of incidence.



Ptychographic X-ray tomography

NATURE 467, 436 (2010)

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Multi keV X-ray ptychography



- + Lens-less \rightarrow high resolution
- + multi-keV X-rays \rightarrow thick samples
 - \rightarrow 3D is important
- + Phase and absorption contrast
- + Quantitative
- Data analysis is involved
- Resolution depends on sample positioning accuracy ightarrow involved instrumentation



Chip imaging in 2D – The Eiger self portrait

Sample 5 mm downstream of focus Beam at sample ~ 10 microns Scanning average step 3.5 microns

Eiger ASIC as sample and Eiger as detector



M. Guizar-Sicairos *et al.*, Opt. Express **22**, 14859 (2014)



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98.4 Mpixel (13,028 x 7,556) Resolution 41 nm, 38.4 nm pixel



M. Guizar-Sicairos *et al.*, Opt. Express **22**, 14859 (2014)

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Two instruments with different sample environements

fIOMNI (flexible tOMography Nano Imaging)

- + nano-positioning, tomography with interferometer
- + room-temperature
- + atmospheric pressure
- + test bench



OMNY (tOMography Nano crYo)

- + optimized mechanical structures
- + cryogenic environment and UHV



M. Holler, et al., Rev. Sci. Instrum. 83, 073703 (2012) M. Holler and J. Raabe, Opt. Eng. 54(5) 054101 (2015) Pat. publication no. WO 2012079875 A1

M. Holler et al., Rev. Sci. Instrum. 89, 043706 (2018) Mirko Holler Page 18



fIOMNI (flexible tOMography Nano Imaging)





Metrology for OMNY: Tracking interferometer

Position sensitive detector measures sphere motion perpendicular to laser beam propagation. Closed loop: interferometer tracks the reference sphere and keeps pointing at its center







Compensation of mechanical tracking error motion needed – details in M. Holler and J. Raabe, Opt. Eng. 54(5) 054101 (2015) Pat. publication no. WO 2012079875 A1



IC imaging – typical sample preparation



UMC 110 nm technology hybrid silicon pixel detector 25 µm pixel pitch



- select region in sample preparation step
- volume limited by thickness, limited by transmission

Holler et al., Nature 543, 402–406 (16 March 2017)



Detector ASIC - tomography result



Holler et al., Nature 543, 402–406 (16 March 2017)



LamNI installed at the cSAXS beamline



M. Holler et al., <u>Nature Electronics</u> 2, 464 (2019) https://rdcu.be/bTudW

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LamNI – measurement of an IC

Photograph of IC measured 16 nm FinFET technology mechanically polished an entire chip of 2.5x2.5 mm² to a substrate thickness of about 20 µm Mounted in LamNI and measured at 6.2 keV two laminograms with an Eiger detector module in air at 2.3 m distance.



Holler et al., in review at Nature



LamNI – measurement of an IC



Low resolution overview scan near-field ptychography, 300x300 μm² (square in sample plane) by stitching 25 regions 70x70 μm² step size of 10 μm 14 sec per projection including all overhead 300 projections



High resolution ptychography scan
circular in sample plane, diameter 40 μm²
485 scan points, 0.7 μm, 0.1 s
76 s per projection incl. all overhead
2872 projections

M. Holler et al., <u>Nature Electronics</u> 2, 464 (2019) https://rdcu.be/bTudW

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LamNI – measurement of an IC – 3D rendering



high-resolution voxel size was 13.0 nm and that volume covers 3800x3800x600 elements

M. Holler et al., Nature Electronics 2, 464 (2019) https://youtu.be/GvyTiK9CNO0

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Questions?

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